

IN THE CLAIMS:

1. to 41. (Canceled)

42. (Currently Amended) A laminate having a layer construction of first inorganic material layer/insulating layer/second inorganic material layer or a layer construction of inorganic material layer/insulating layer,

said insulating layer having a multi-layer structure of two or more resin layers,

the ratio of the etching rate of the resin layer ~~having a higher etching rate to the etching rate of the resin layer having a lower etching rate~~ layers being in the range of 6 : 1 to 1 : 1.

43. (Currently Amended) The laminate according to claim 42, wherein the ratio of the etching rate of the resin layer ~~having a higher etching rate to the etching rate of the resin layer having a lower etching rate~~ layers is in the range of 4 : 1 to 1 : 1.

Serial No.: 10/069,047

44. (Previously Presented) The laminate according to claim 42, wherein the insulating layer comprises a core insulating layer and an adhesive layer provided on both sides of the core insulating layer.

45. (Original) The laminate according to claim 44, wherein the strength of bonding of the adhesive layer to the inorganic material layer and the core insulating layer is at least 300 g/cm.

46. (Original) The laminate according to claim 44, wherein the thickness ratio of the core insulating layer to each of the adhesive layers is up to 4 : 1.

47. (Previously Presented) The laminate according to claim 42, wherein at least one of the layers constituting the insulating layer is formed of a polyimide resin.

48. (Previously Presented) The laminate according to claim 42, wherein all the layers constituting the insulating layer are formed of a polyimide resin.

Serial No.: 10/069,047

49. (Previously Presented) The laminate according to claim 42, wherein the etching rate ratio in the insulating layer is a value as measured in etching with an alkali solution.

50. (Previously Presented) The laminate according to claim 42, wherein the inorganic material constituting the laminate is selected from copper, alloy copper, and stainless steel.

51. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42.

52. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42 by a wet process.

53. (Previously Presented) An electronic circuit component produced by etching the laminate according to claim 42 by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal in the etching.

54. (Previously Presented) A suspension for a hard disk drive, produced by etching the laminate according to claim 42 by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the removal in the etching.

55. (Currently Amended) An insulating film comprising two or more resin layers, the ratio of the etching rate of the resin ~~layer having a higher etching rate to the etching rate of the resin layer having a lower etching rate~~ layers being in the range of 6 : 1 to 1 : 1.

56. (Currently Amended) The insulating film according to claim 55, wherein the ratio of the etching rate of the resin ~~layer having a higher etching rate to the etching rate of the resin layer having a lower etching rate~~ layers is in the range of 4 : 1 to 1 : 1.

57. (Original) The insulating film according to claim 55, wherein at least one of the resin layers is formed of a polyimide resin.

Serial No.: 10/069,047

58. (Original) The insulating film according to claim 55, wherein all the resin layers constituting the insulating layer are formed of a polyimide resin.

59. (Original) A laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other.

60. (Original) An electronic circuit component produced by etching the laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other.

61. (Original) An electronic circuit component produced by etching the laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process.

62. (Original) An electronic circuit component produced by etching the laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process, an inorganic nitride layer and/or an inorganic

Serial No.: 10/069,047

fluoride layer being absent on the surface of the inorganic material layer exposed by the etching.

63. (Original) A suspension for a hard disk drive, produced by etching the laminate comprising the insulating film according to claim 55 and an inorganic material stacked on top of each other by a wet process, an inorganic nitride layer and/or an inorganic fluoride layer being absent on the surface of the inorganic material layer exposed by the etching.